



Product Disassembly Instructions

Product Category: <u>Panel PC</u> Product Marketing Name / Model: <u>PPC-6151C-RTAE/PPC-6171C-RTAE/PPC-6191C-RTAE</u>

Purpose: The document provides the basic instructions for the disassembly of products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC and 2012/19/EU, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq. cm Mother board, Card Reader board, USB Daughter board, LID Daughter board	4
Batteries	All types including standard alkaline and lithium coin or button style batteries 6cell battery or 9 cell battery, and RTC battery	0
External electrical cables and Power cord		0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Gas Discharge Lamps		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0

1.1 Items listed below are classified as requiring selective treatment.

Item Description	Notes	Quantity of items included in product
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Capacitors / condensers (Containing PCB)		0

Plastics containing Brominated Flame Retardants weighing > 25 grams	(Not including PCBs or PCAs already listed as a separate item above)	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Asbestos waste and components which contain asbestos		0
Components containing refractory ceramic fibers		0
Chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons(HFC), hydrocarbons (HC)		0
Components, parts and materials containing radioactive substances		0





2.0 Disassembly Tool

List the tools that would typically be used to disassemble the product to a point where components and materials can be removed.

Disassembly Tool	Picture
Screwdriver	0
Lever	
Star Screwdriver	0
Hexagon Driver	0
Slanted pliers	<pre></pre>
Pliers	1
Hammer	8
Knife	



3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials.

A. Disassembly Box module.

- A-1. Disassembly 6 pcs screw to remove the Rear cover.
- A-2. Disassembly 2 pcs Antenna rubber.
- A-3. Disassembly 4 pcs screw to remove the strength bracket module.
- A-4. Disassembly 8 pcs screw to remove the FAN.
- A-5. Disassembly 4 pcs screw to remove the HDD/SSD module
- A-6. Disassembly 4 pcs screw to remove the HDD/SSD
- A-7. Disassembly 6 pcs screw to remove the IO bracket Module
- A-8. Disassembly 4 pcs screw to remove the PCE/E bracket Module
- A-9. Disassembly 2 pcs screw to remove the PCE/E Block slice
- A-10. Disassembly Power button from IO bracket.
- A-11. Disassembly 2 pcs screw to remove Power module.
- A-12. Disassembly 2 pcs screw to remove Power bracket.
- A-13. Disassembly 4 pcs screw to remove Speaker Module.

B. Disassembly Panel module.

- B-1. Disassembly 7 pcs screw to remove the MB frame.
- B-2. Disassembly screw 4pcs to remove the LCD sub-assembly from Front Bezel.
- B-3. Disassembly screw 4pcs to separate the LCD bracket left and right with LCD module.
- B-4. Separate the LCD sponge from LCD opening bezel.
- B-5. Disassembly screw 1pcs to remove the LED indicator board.
- B-6. Remove the waterproof from front bezel.



3.2 Exploded view drawing. Insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

